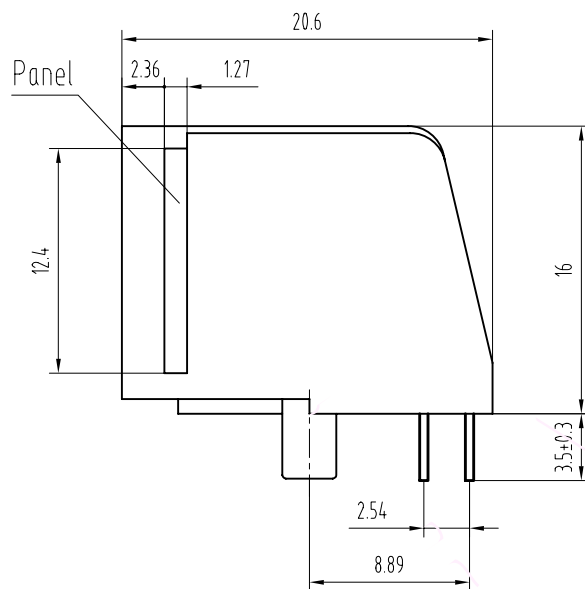
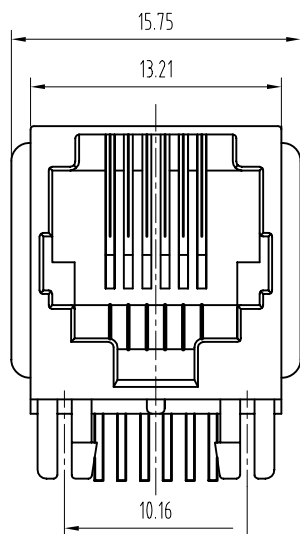
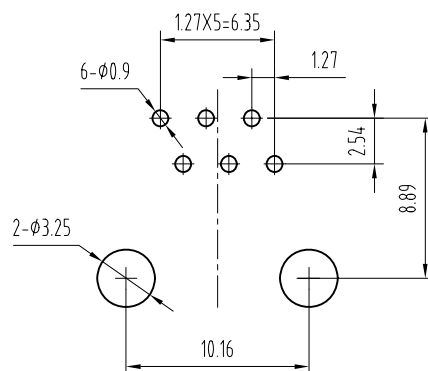
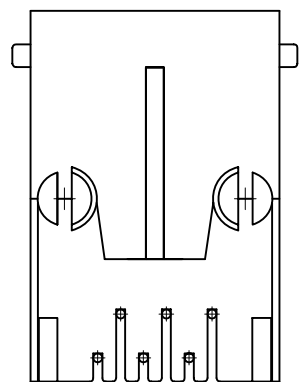




PCB LAYOUT



NOTES:

ELECTRICAL:

- | | |
|-------------------------|------------------------------|
| 1.VOLTAGE RATING | :125 VAC RMS. |
| 2.CURRENT RATING | :1.5 AMP. |
| 3.CONTACT RESISTANCE | :30 MILLIOHMS MAX. |
| 4.INSULATION RESISTANCE | :500 MEGOHMS MIN @ 500V DC . |
| 5.DIELECTRIC STRENGTH | :1000V AC RMS 50Hz. 1MIN. |

MECHANICAL:

- | | |
|----------------------------|------------------------------------|
| 1.HOUSING MATERIAL | :GLASS FILLED POLYESTER UL94V-0. |
| 2.CONTACT MATERIAL | :PHOSPHOR BRONZE T=0.35mm FLAT PIN |
| 3.PLATING | :GOLD PLATING OVER NICKEL. |
| 4.OPERATING | :750 CYCLES MIN. |
| 5.PCB RETENTION PRE-SOLDER | :1 LB MIN. |

ENVIRONMENTAL:

- | | |
|---------------------|------------------|
| 1.Temperature Range | : -40℃~+85℃ |
| 2.Relative Humidity | : 90~95% (40±2℃) |



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X." ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: RJ11 6P6C 90 ° DIP
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW29-RJ11-206B
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-RJ17022616
			SHEET NO. 1 OF 1